

Amendments to the Claims:

1. (Original) A circuit electrode bonding method for bonding a bonding portion of a circuit electrode to a bonding material in an environment at a first temperature, the bonding portion and the bonding material being used in an environment at a second temperature which is different from the first temperature, the method comprising the steps of:

measuring an actual size of the bonding portion of the circuit electrode at the first temperature;

comparing the actual size of the bonding portion with a designed size of the bonding portion at the first temperature; and

determining a cutting size of the bonding material based on a comparison result and mounting the bonding material over the bonding portion.

2. (Original) The circuit electrode bonding method according to claim 1, further comprising the steps of:

calculating a location of the bonding portion based on the comparison result; and

mounting the bonding material over the bonding portion in the calculated location.

3. (Original) The circuit electrode bonding method according to claim 1, further comprising the step of converting the actual size of the bonding material into a size for the second temperature.

4. (Original) The circuit electrode bonding method according to claim 1, further comprising the step of correcting the actual size of the bonding material based on a processing error caused in the step of mounting the bonding material over the bonding portion.

5. (Original) The circuit electrode bonding method according to claim 1, wherein the number of times the steps of measuring the actual size of the bonding portion and comparing the actual size of the bonding portion with the designed size of the bonding portion are performed is equal to or more than the number of times the bonding portion is formed.

6. (Original) The circuit electrode bonding method according to claim 1, wherein the steps of measuring the actual size of the bonding portion of the circuit electrode;

comparing the actual size of the bonding portion with the designed size of the bonding portion; and determining the cutting size of the bonding material based on the comparison result and mounting the bonding material over the bonding portion are repeatedly performed.

7. (Currently Amended) The circuit electrode bonding method according to claim 1 ~~any one of claims 1-5~~, wherein the bonding material is selected from the group consisting of an anisotropic conductive film, a thermosetting resin film, a conductive resin paste, and a thermosetting resin paste.

8. (Original) A circuit electrode bonding apparatus comprising:

a measuring section for measuring a size of a bonding portion of a circuit electrode;

a comparing section for comparing the measured size of the bonding portion with a designed size of the bonding portion;

a size determination section for determining a processing size of the bonding material based on a comparison result;

a processing section for processing the bonding material to the processing size;

a mounting section for mounting the processed bonding material over the bonding portion;

and

a location determination section for determining a location of the bonding portion based on the comparison result.

9. (New) The circuit electrode bonding method according to claim 2, wherein the bonding material is selected from the group consisting of an anisotropic conductive film, a thermosetting resin film, a conductive resin paste, and a thermosetting resin paste.

10. (New) The circuit electrode bonding method according to claim 3, wherein the bonding material is selected from the group consisting of an anisotropic conductive film, a thermosetting resin film, a conductive resin paste, and a thermosetting resin paste.

11. (New) The circuit electrode bonding method according to claim 4, wherein the bonding material is selected from the group consisting of an anisotropic conductive film, a thermosetting resin film, a conductive resin paste, and a thermosetting resin paste.

12. (New) The circuit electrode bonding method according to claim 5, wherein the bonding material is selected from the group consisting of an anisotropic conductive film, a thermosetting resin film, a conductive resin paste, and a thermosetting resin paste.